

Abstract**A thermally crosslinkable heat-sealing adhesive**

A mixture of an adduct of an epoxy resin and a novolak with an acrylate polymer, a modified bisphenol A or a polyol in conjunction with a polyisocyanate or a polyol of an OH-terminated polyurethane or polyester gives a heat-sealing adhesive combining high heat resistance and good hydrolysis stability with relatively high bond strengths. Accordingly, the composition is suitable above all as a base material and cover film for printed circuits.

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